

2SK2225

Silicon N Channel MOS FET

Application

High speed power switching

Features

- High breakdown voltage ($V_{DSS} = 1500$ V)
- High speed switching
- Low drive current
- No Secondary Breakdown
- Suitable for Switching regulator, DC – DC converter

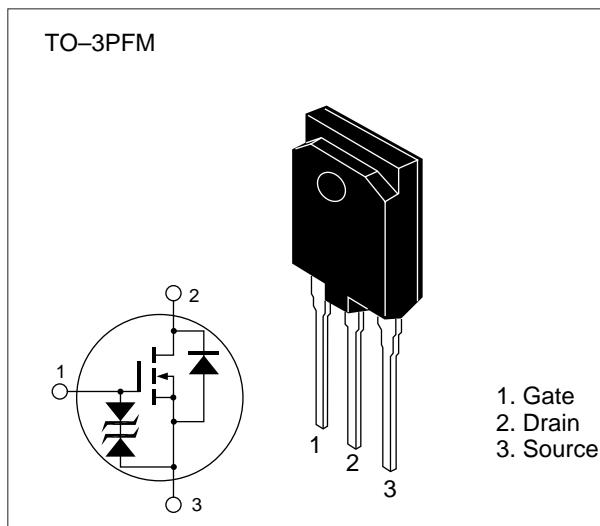


Table 1 Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	1500	V
Gate to source voltage	V_{GSS}	± 20	V
Drain current	I_D	2	A
Drain peak current	$I_{D(\text{pulse})}^*$	7	A
Body-drain diode reverse drain current	I_{DR}	2	A
Channel dissipation	P_{ch}^{**}	50	W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

* PW ≤ 10 µs, duty cycle ≤ 1 %

** Value at $T_c = 25$ °C

Table 2 Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	1500	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source leak current	I _{GSS}	—	—	±1	µA	V _{GS} = ±20 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	500	µA	V _{DS} = 1200 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	2.0	—	4.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state resistance	R _{DS(on)}	—	9	12	Ω	I _D = 1 A V _{GS} = 15 V *
Forward transfer admittance	y _{fs}	0.45	0.75	—	S	I _D = 1 A V _{DS} = 20 V *
Input capacitance	C _{iss}	—	990	—	pF	V _{DS} = 10 V
Output capacitance	C _{oss}	—	125	—	pF	V _{GS} = 0
Reverse transfer capacitance	C _{rss}	—	60	—	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	—	17	—	ns	I _D = 1 A
Rise time	t _r	—	50	—	ns	V _{GS} = 10 V
Turn-off delay time	t _{d(off)}	—	150	—	ns	R _L = 30 Ω
Fall time	t _f	—	50	—	ns	
Body-drain diode forward voltage	V _{DF}	—	0.9	—	V	I _F = 2 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	—	1750	—	ns	I _F = 20 A, V _{GS} = 0, diF / dt = 100 A / µs

* Pulse Test

